



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSC110N06NS3 G	<b>Issued</b>	12. April 2021
<b>MA#</b>	MA002337720		
<b>Package</b>	PG-TDSON-8-40	<b>Weight*</b>	111.96 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.281	1.14	1.14	11441	11441
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		131	
	non noble metal	iron	7439-89-6	0.049	0.04		435	
	non noble metal	copper	7440-50-8	48.649	43.48	43.53	434521	435087
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	530	530
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		747	
	plastics	epoxy resin	-	6.610	5.90		59043	
	inorganic material	silicondioxide	60676-86-0	35.144	31.39	37.36	313898	373688
leadfinish	non noble metal	tin	7440-31-5	1.520	1.36	1.36	13577	13577
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1415	1415
solder	non noble metal	tin	7440-31-5	0.029	0.03		261	
	noble metal	silver	7440-22-4	0.036	0.03		326	
	non noble metal	lead	7439-92-1	1.393	1.24	1.30	12443	13030
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.910	15.10	15.12	151036	151232
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com